

DESCRIPTION:

With high ability to withstand the shock loading of large current, **VSA12/VSB12** triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



MAIN FEATURES

Symbol	ool Value	
I _{T(RMS)}	12	Α
V _{DRM} /V _{RRM}	600/800/1200	V



ABSOLUTE MAXIMUM RATINGS

Pa	arameter	Symbol	Value	Unit		
Storage junction temperature range		T _{stg}	-40-150	$^{\circ}$		
Operating junction	Operating junction temperature range		Operating junction temperature range		-40-125	$^{\circ}$
Repetitive peak off-state voltage (Tj=25℃)		VDRM	600/800/1200	V		
Repetitive peak reverse voltage (T _j =25℃)		VRRM	600/800/1200	V		
Non repetitive surge peak Off-state voltage		V _{DSM}	V _{DRM} +100	V		
Non repetitive peak reverse voltage		V _{RSM}	V _{RRM} +100	V		
	TO-220A(Ins) (Tc=85°C)					
RMS on-state current	TO-262/ TO-220B(Non-Ins)/ TO-220C(Tc=100°C) TO-220F(Ins) (Tc=80°C)	I _{T(RMS)}	12	А		



Non repetitive surge peak on-state current (full cycle, F=50Hz)		Ітѕм	120	А
I ² t value for fusing (tp=10ms)		l²t	78	A ² s
Critical rate of rise of on-state current (I _G =2×I _{GT})		dl/dt	50	A/µs
Peak gate current		Івм	4	Α
Average gate power dissipation		P _{G(AV)}	1	W
Peak gate power		P _{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j=25°C unless otherwise specified)

3 Quadrants

Symbol	Test Condition Quadrant		Value			Unit		
		Quadrant	BW	CW	sw	TW	Oilit	
Іст	V _D =12V R _L =33Ω	I - II -III	MAX	50	35	10	5	mA
V _{GT}	VD=12V RL=3312	I - II -III	MAX	1.3			V	
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2			V	
I.	1 4 01	I -III	NAAV	80	50	30	20	m 1
lL	IG =1.2IGT	II	MAX	90	60	40	30	mA
lμ	I _T =100mA		MAX	60	40	20	15	mA
dV/dt	V _D =2/3V _{DRM} Gate Ope	en Tj=125℃	MIN	1000	500	200	100	V/µs
(dl/dt)c	Without snubber T _j =	=125℃	MIN	12	6.5	-	1-	A/ms

4 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				В	С	Offic
la-	I _{GT} V _D =12V R _L =33Ω	I - II -III	MAX	50	25	mA
IGT		IV		70	50	
V _G T		ALL	MAX	1.	.3	V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	ALL	MIN	0.2		V
IL	I _L I _G =1.2I _{GT} I -III-IV	MAY	50	40	mA	
		II	MAX	100	80	

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Ін	I _T =100mA	MAX	50	25	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃	MIN	500	200	V/µs
(dV/dt)c	(dl/dt)c=5.3A/ms T _j =125℃	MIN	10	5	V/µs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V _{TM}	I _{тм} =17A tp=380µs	T _j =25℃	1.5	V
IDRM	N - N - N	T _j =25℃	5	μΑ
I _{RRM}	V _D =V _{DRM} V _R =V _{RRM}	Tj=125℃	1	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
		TO-220A(Ins)	2.3	
R _{th(j-c)}	junction to case(AC)	TO-262/ TO-220B(Non-Ins)/ TO-220C	1.4	°C/W
		TO-220F(Ins)	2.5	



FIG.1 Maximum power dissipation versus RMS on-state current

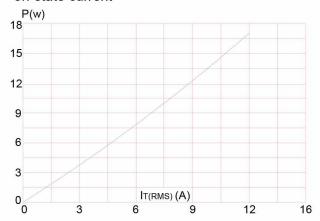
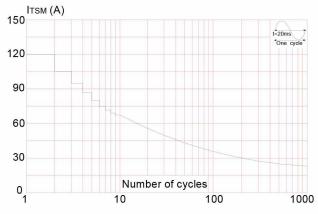


FIG.3: Surge peak on-state current versus number of cycles



corresponging value of l²t (dl/dt(- - - - - - -) < 50A/μs)

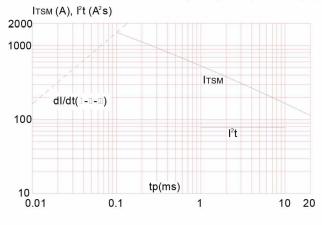


FIG.2: RMS on-state current versus case temperature

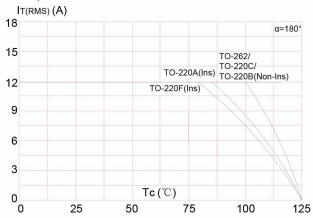
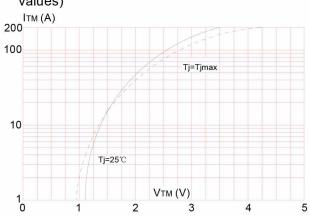


FIG.4: On-state characteristics (maximum values)



junction temperature

